

C1812C272GATACTU

Aliases (C1812C272GATAC7800)

SMD Comm X8G HT150C, Ceramic, 2,700 pF, 2%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information			
Series	SMD Comm X8G HT150C		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Typical Component Weight	67 mg		
Shelf Life	78 Weeks		
MSL	1		

2,700 pF

1 kHz 1.0Vrms

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

VV	3.211111 +/ -0.311111
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm
Packaging Specifications	

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W	3.2mm +/-0.3mm	Tolerance	2% 250 VDC	
Т	1mm +/-0.10mm	Voltage DC		
S	2.3mm MIN	Dielectric Withstanding Voltage	625 VDC	
В	0.6mm +/-0.35mm	Temperature Range	-55/+150°C	
		Temp. Coefficient	X8G	
Packaging Specifications		Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms	
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)		
Packaging Quantity 10	1000	Dissipation Factor	0.1% 1 kHz 1.0Vrms	
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
		Insulation Resistance	100 GOhms	

Specifications

Measurement Condition

Capacitance

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